



ICMSSM2020

2020 6th International Conference on Mechanical Structures and Smart

July 25-26, 2020

Ho Chi Minh City, Vietnam

The aim of ICMSSM2020 is to provide a platform for researchers, engineers, and academicians, as well as industrial professionals, to present their research results and development activities in Mechanical Structures and Smart Materials Related Issue.

[Publication]

Papers submitted to ICMSSM2020 will be reviewed by technical committees of the conference. All accepted and registered papers will be published in **"Materials Science Forum"** [ISSN print 0255-5476 ISSN cd 1662-9760 ISSN web 1662-9752, Trans Tech Publications]. And the press will submit all papers to major databases such as **El Compendex, Scopus and Scholar...**

You can attend the conference as a **listener, presenter** (for poster) or author (for **full paper**).

Topics (not limited to)

- T1: Smart materials
- T2: Material Science and Engineering
- T3: Mechanical engineering and mechatronics
- T4: Materials Manufacturing and Processing

For more topics, please click:

<http://www.icmssm.org/pages/cfp.html>

Paper Submission

1. Submit by CMT system :
<https://cmt3.research.microsoft.com/ICMSSM2020>
2. Email: cfp@icmssm.org

Important Dates

Submission Deadline: June 20, 2020

Registration Due: July 2, 2020

Acceptance Notification: June 25, 2020

Conference Date: July 25-26, 2020

Contact us

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